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U.S. DEPARTMENT OF COMMERCE
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Attorney Docket No. 501-4335X00

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
Akio HASEBE
Yasunori NARIZUKA
Yasuhiro MOTOYAMA
Teruo SHOJI

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)
 Name: **RENESAS TECHNOLOGY CORP.**
 Address: **4-1, Marunouchi 2-chome, Chiyoda-ku, Tokyo, Japan**

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10/20/04

3. Nature of conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other

Execution Date: **September 13, 14, 6, and 6, 2004.**

Additional name(s) & address(es) attached? Yes No

4. Application number(s) or patent number(s):
 If this document is being filed together with a new application, the execution date of the application is: **September 13, 14, 6, and 6, 2004.**
 A. Patent Application No.(s)
 B. Patent Registration No.(s)

Additional number(s) attached Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:
 Name: **ANTONELLI, TERRY, STOUT & KRAUS, LLP**
 Internal Address:
1300 NORTH 17TH STREET - SUITE 1800
 City: **ARLINGTON** State: **VA** Zip **22209**

6. Total number of applications and patents involved 1

7. Total fee (37 CFR 3.41)..... **\$40.00**
 Enclosed
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8. Deposit account number:
01-2135

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9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

WILLIAM I. SOLOMON, Reg#28,565
 Name of Person Signing

William I. Solomon
 Signature

10/20/2004
 Date

Total number of pages including cover sheet, attachments, and document: 2

Mail documents to be recorded with required cover sheet information to:
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PATENT
 REEL: 015915 FRAME: 0794

ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Technology Corp., a corporation organized under the laws of Japan, located at 4-1, Marunouchi 2-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Technology Corp., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

FABRICATION METHOD OF SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Renesas Technology Corp., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Technology Corp.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Akio HASEBE Akio HASEBE</u>	<u>13/September/2004</u>
2) <u>Masunori Shoji NARIZUKA Yasunori NARIZUKA</u>	<u>14/September/2004</u>
3) <u>Yasuhito Motoyama Yasuhiro MOTOYAMA</u>	<u>6/September/2004</u>
4) <u>Teruo Shoji Teruo SHOJI</u>	<u>6/September/2004</u>
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____